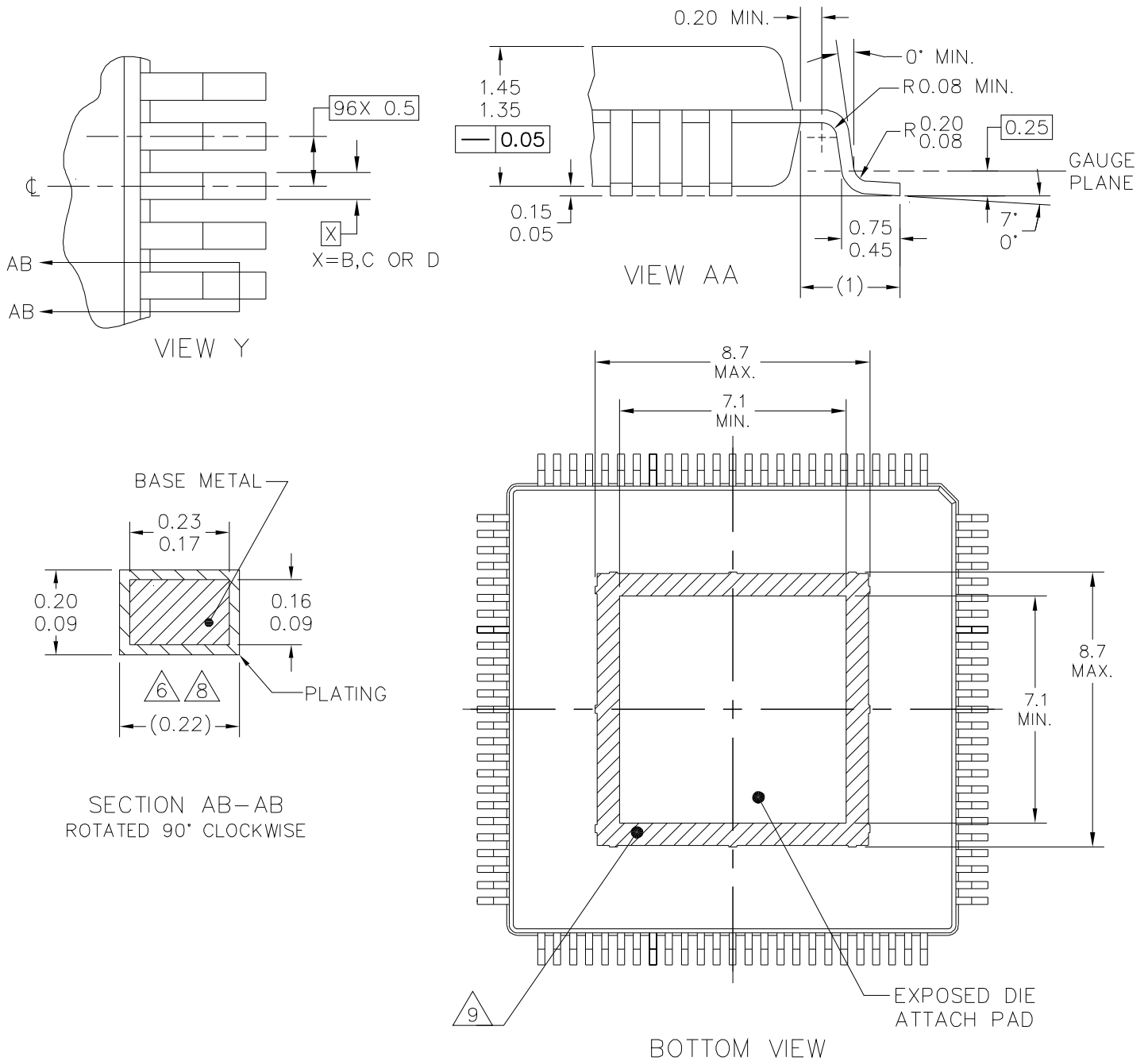


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TITLE: LQFP, 14 X 14 X 1.4 PKG, 0.5 PITCH, 100LD, 7.9 X 7.9 EXPOSED PAD		DOCUMENT NO: 98ASA00553D	REV: B
		STANDARD: NON-JEDEC	
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NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.

2. DIMENSIONS IN MILLIMETERS.

3. DATUMS B-C AND D TO BE DETERMINED AT DATUM PLANE H.

4. THIS DIMENSIONS TO BE DETERMINED AT SEATING PLANE, DATUM A.

5. THIS DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. THIS DIMENSIONS INCLUDE MOLD MISMATCH.

6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 mm FROM THE LEAD TIP.

9. HATCHED AREA TO BE KEEP-OUT ZONE FOR PCB ROUTING.

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